



StratEdge Offers Assembly Services for Die Attachment on CMC Tabs

StratEdge experts available at BCICTS 2019 to analyze your high-frequency packaging needs

High Resolution Photo at:

<https://www.stratedge.com/assembly-services.png>

Santee, Calif - October 24, 2019 - [StratEdge Corporation](#), leader in the design, production, and assembly of high-frequency and high-power semiconductor packages for microwave, millimeter-wave, and high-speed digital devices, announces its assembly services for attaching gallium nitride (GaN) and other high-frequency, high-power devices using gold-tin (AuSn) and gold-silicon (AuSi) onto copper-molybdenum-copper (CMC) tabs. StratEdge's proprietary eutectic die attach method maximizes the power output a chip can achieve, optimizing its performance and providing an efficient way to dissipate heat to avoid overheating and failures during normal operation.



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StratEdge uses the latest high-volume automated system in a cleanroom environment to perform eutectic AuSn die attach of compound semiconductor devices that have a backside gold surface finish. The bonder has micron placement accuracy. Solder preforms are matched to the size of the die to reduce solder bond line thickness to less than $6\mu\text{m}$, maximizing power output for GaN devices, lowering junction temperatures, and increasing device reliability. For silicon devices, a AuSi eutectic die attach method is used to create a reliable solder joint with excellent thermal dissipation.

"GaN on CMC is perfect for chip-on-board (COB) applications because organic boards cannot withstand the eutectic die attach temperature," said Casey Krawiec, VP of global sales for StratEdge Corporation. "Eutectic die attach is a highly controlled die attach process that provides void-free, high-reliability, high-accuracy chip attachment. The chip's performance benefits from the superior

thermal characteristics of the CMC heat spreader before the chip is installed onto the board. StratEdge provides the service along with the custom-built CMC tabs, which allows the chip to be placed directly on a layer of high thermally conductive copper."

StratEdge will be exhibiting at the 2019 IEEE BiCMOS and Compound Semiconductor Integrated Circuits and Technology Symposium (BCICTS) in Booth 10. BCICTS is being held at the Loews Vanderbilt Hotel, Nashville, TN, from November 3-6.

For more information, contact StratEdge at info@stratedge.com, shop at the StratEdge store on [Amazon.com](https://www.amazon.com), and/or visit our website at www.stratedge.com.

About StratEdge Corporation

StratEdge Corporation, founded in 1992, designs, manufactures, and provides assembly services for a complete line of high frequency and high power semiconductor packages operating from DC to 63+ GHz. StratEdge offers post-fired ceramic, low-cost molded ceramic, and ceramic QFN packages, and specializes in packages for extremely demanding gallium arsenide (GaAs) and gallium nitride (GaN) devices. Markets served include telecom, VSAT, broadband wireless, satellite, military, test and measurement, automotive, clean energy, and down-hole. All packages are lead-free and most meet RoHS and WEEE standards. StratEdge is an ISO 9001:2015 certified facility located in Santee, California, near San Diego.

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